

PATENT ABSTRACTS OF JAPAN

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(21)Application number : 04-231107 (71)Applicant : KYOCERA CORP

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(54) CIRCUIT BOARD AND METHOD FOR FORMING ELECTRODE OF CIRCUIT BOARD**(57)Abstract:**

PURPOSE: To prevent connection failure by facilitating connection of a circuit board to a mother board and by reducing dispersion in height of bumps.

CONSTITUTION: This circuit board comprises a plurality of boards 2 surfaced with surface electrodes 4 and containing outer lead wiring layers 3, and having electrode holes 8 to expose outer lead wiring layers 3 and electrode solder balls filling the electrode holes 8 and hot-melted to the outer lead wiring layers 3 so as to be exposed partially from the rear of the board main body.

